



Precision LVDS 1:20 Fanout with 2:1 MUX and Internal Termination with Fail-Safe Input

General Description

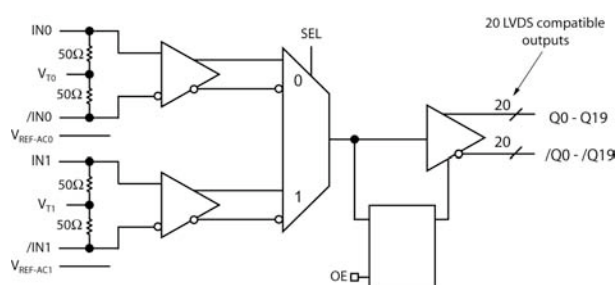
The SY89468U is a 2.5V, 1:20 LVDS fanout buffer with a 2:1 differential input multiplexer (MUX). A unique Fail-Safe Input (FSI) protection prevents metastable output conditions when the selected input clock fails to a DC voltage (voltage between the pins of the differential input drops significantly below 100mV).

The differential input includes Micrel's unique, 3-pin internal termination architecture that can interface to any differential signal (AC- or DC-coupled) as small as 100mV (200mV_{PP}) without any level shifting or termination resistor networks in the signal path. The outputs are LVDS compatible with very fast rise/fall times guaranteed to be less than 270ps.

The SY89468U operates from a 2.5V $\pm 5\%$ supply and is guaranteed over the full industrial temperature range of -40°C to $+85^{\circ}\text{C}$. The SY89468U is part of Micrel's high-speed, Precision Edge[®] product line.

All support documentation can be found on Micrel's web site at: www.micrel.com.

Functional Block Diagram



Precision Edge[®]

Features

- Selects between two inputs, and provides 20 precision LVDS copies
- Fail-Safe Input
 - Prevents outputs from oscillating when input is invalid
- Guaranteed AC performance over temperature and supply voltage:
 - DC to $>1.5\text{GHz}$ throughput
 - $< 1200\text{ps}$ Propagation Delay (In-to-Q)
 - $< 270\text{ps}$ Rise/Fall times
- Ultra-low jitter design:
 - $< 1\text{ps}_{\text{RMS}}$ random jitter
 - $< 1\text{ps}_{\text{RMS}}$ cycle-to-cycle jitter
 - $< 10\text{ps}_{\text{PP}}$ total jitter (clock)
 - $< 0.7\text{ps}_{\text{RMS}}$ MUX crosstalk induced jitter
- Unique, patented MUX input isolation design minimizes adjacent channel crosstalk
- Unique, patented internal termination and VT pin accepts DC- and AC-coupled inputs (CML, PECL, LVDS)
- Wide input voltage range VCC to GND
- 2.5V $\pm 5\%$ supply voltage
- -40°C to $+85^{\circ}\text{C}$ industrial temperature range
- Available in 64-pin EPAD-TQFP package

Applications

- Fail-safe clock protection
- Ultra-low jitter LVDS clock or data distribution
- Rack-based Telecom/Datacom

Markets

- LAN/WAN
- Enterprise servers
- ATE
- Test and measurement

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November 2008

M9999-110308-D

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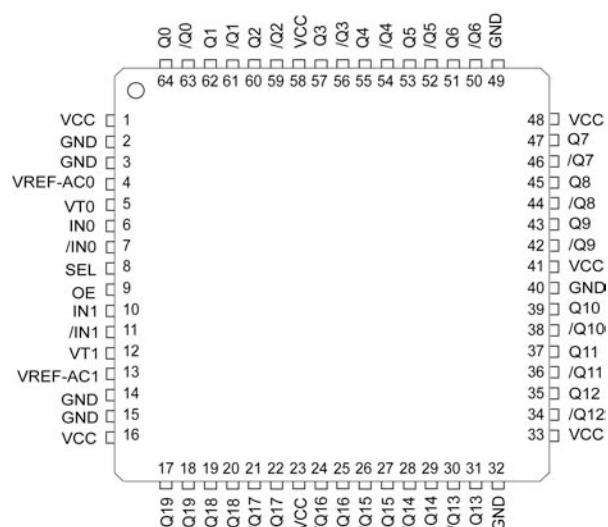
Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY89468UHY	H64-1	Industrial	SY89468UHY with Pb-Free bar-line Indicator	Matte-Sn Pb-Free
SY89468UHYTR ⁽²⁾	H64-1	Industrial	SY89468UHY with Pb-Free bar-line Indicator	Matte-Sn Pb-Free

Notes:

1. Contact factory for die availability. Dice are guaranteed at $T_A = 25^\circ\text{C}$, DC Electricals Only.
2. Tape and Reel.

Pin Configuration



64-Pin EPAD-TQFP (H64-1)

Pin Description

Pin Number	Pin Name	Pin Function
1, 16, 23, 33 41, 48, 58	VCC	Positive Power Supply: Bypass with 0.1 μ F 0.01 μ F low ESR capacitors as close to the V _{CC} pins as possible.
64, 63 62, 61 60, 59 57, 56 55, 54 53, 52 51, 50 47, 46 45, 44 43, 42 39, 38 37, 36 35, 34 31, 30 29, 28 27, 26 25, 24 22, 21 20, 19 18, 17	Q0, /Q0 Q1, /Q1 Q2, /Q2 Q3, /Q3 Q4, /Q4 Q5, /Q5 Q6, /Q6 Q7, /Q7 Q8, /Q8 Q9, /Q9 Q10, /Q10 Q11, /Q11 Q12, /Q12 Q13, /Q13 Q14, /Q14 Q15, /Q15 Q16, /Q16 Q17, /Q17 Q18, /Q18 Q19, /Q19	Differential Output Pairs: The output swing is typically 325mV. Used and unused outputs must be terminated with 100 Ω across the pair (Q, /Q). These differential LVDS outputs are a logic function of the IN0, IN1, and SEL inputs. See "Truth Table" below.
4, 13	VREF-AC0 VREF-AC1	Reference Voltage: These outputs bias to V _{CC} -1.2V. They are used for AC-coupling inputs IN and /IN. Connect VREF-AC directly to the corresponding VT pin. Bypass with 0.01 μ F low ESR capacitor to VCC. Due to limited drive capability, each VREF-AC pin is only intended to drive its respective VT pin. Maximum sink/source current is ± 0.5 mA. See "Input Interface Applications" subsection.
5, 12	VT0, VT1	Input Termination Center-Tap: Each side of a differential input pair terminates to the VT pin. The VT pin provides a center-tap for each input (IN, /IN) to a termination network for maximum interface flexibility. See "Input Interface Applications" subsection.
6, 7 10, 11	IN0, /IN0 IN1, /IN1	Differential Inputs: These input pairs are the differential signal inputs to the device. These inputs accept AC- or DC-coupled signals as small as 100mV. The input pairs internally terminate to a VT pin through 50 Ω . Each input has level shifting resistors of 3.72k Ω to VCC. This allows a wide input voltage range from VCC to GND. See Figure 3, Simplified Differential Input Stage for details. Note that when these inputs are left in an open state, the FSI feature will override this input state and provide a valid state at the output. See "Functional Description" subsection.
2, 3, 14, 15, 32, 40, 49	GND, Exposed Pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pins.
9	OE	Single-Ended Input: This TTL/CMOS input disables and enables the Q0-Q19 outputs. It is internally connected to a 25k Ω pull-up resistor and will default to a logic HIGH state if left open. When disabled, Q goes LOW and /Q goes HIGH. OE being synchronous, outputs will be enabled/disabled following a rising and a falling edge of the input clock. V _{TH} = V _{CC} /2.
8	SEL	Single-Ended Input: This single-ended TTL/CMOS-compatible input selects the inputs to the multiplexer. Note that this input is internally connected to a 25k Ω pull-up resistor and will default to logic HIGH state if left open. V _{TH} = V _{CC} /2.

Truth Table

Inputs					Outputs	
IN0	/IN0	IN1	/IN1	SEL	Q	/Q
0	1	X	X	0	0	1
1	0	X	X	0	1	0
X	X	0	1	1	0	1
X	X	1	0	1	1	0

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC}) -0.5V to +4.0V
 Input Voltage (V_{IN}) -0.5V to V_{CC}
 LVDS Output Current (I_{OUT}) ± 10 mA
 Current (V_T)
 Source or sink on V_T pin ± 100 mA
 Input Current
 Source or sink current on (IN, /IN) ± 50 mA
 Current (V_{REF})
 Source/Sink Current on V_{REF-AC} ⁽⁴⁾ ± 0.5 mA
 Maximum operating Junction Temperature 125°C
 Lead Temperature (soldering, 20 sec.) +260°C
 Storage Temperature (T_s) -65°C to 150°C

Operating Ratings⁽²⁾

Supply Voltage (V_{CC}) +2.375V to +2.625V
 Ambient Temperature (T_A) -40°C to +85°C
 Package Thermal Resistance ⁽³⁾
 TQFP (θ_{JA})
 Still-Air 35°C/W
 TQFP (ψ_{JB})
 Junction-to-Board 21°C/W

DC Electrical Characteristics⁽⁵⁾

$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply		2.375	2.5	2.625	V
I_{CC}	Power Supply Current	No load, max V_{CC}		260	365	mA
R_{IN}	Input Resistance (IN-to- V_T)		45	50	55	Ω
R_{DIFF_IN}	Differential Input Resistance (IN-to-/IN)		90	100	110	Ω
V_{IH}	Input High Voltage (IN, /IN)		0.1		V_{CC}	V
V_{IL}	Input Low Voltage (IN, /IN)		0		$V_{IH}-0.1$	V
V_{IN}	Input Voltage Swing (IN, /IN)	See Figure 2a. Note 6.	0.1		1.0	V
V_{DIFF_IN}	Differential Input Voltage Swing IN-/IN	See Figure 2b.	0.2			V
V_{IN_FSI}	Input Voltage Threshold that Triggers FSI			30	100	mV
V_{REF-AC}	Output Reference Voltage	$I_{VREF-AC} = \pm 0.5$ mA	$V_{CC}-1.3$	$V_{CC}-1.2$	$V_{CC}-1.1$	V
V_{T_IN}	Voltage from Input to V_T				1.28	V

Notes:

- Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. θ_{JA} and ψ_{JB} values are determined for a 4-layer board in still air unless otherwise stated.
- Due to limited drive capability use for input of the same package only.
- The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- $V_{IN}(\text{max})$ is specified when V_T is floating.

LVDS Outputs DC Electrical Characteristics⁽⁷⁾

$V_{CC} = +2.5V \pm 5\%$, $R_L = 100\Omega$ across the outputs; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OUT}	Output Voltage Swing (Q, /Q)	See Figure 2a	250	325		mV
V_{DIFF_OUT}	Differential Output Voltage Swing Q – /Q	See Figure 2b	500	650		mV
V_{OCM}	Output Common Mode Voltage (Q, /Q)	See Figure 5a	1.125	1.20	1.275	V
ΔV_{OCM}	Change in Common Mode Voltage (Q, /Q)	See Figure 5b	–50		+50	mV

LVTTL/CMOS DC Electrical Characteristics⁽⁷⁾

$V_{CC} = 2.5V \pm 5\%$; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V
I_{IH}	Input HIGH Current		–125		30	μA
I_{IL}	Input LOW Current		–300			μA

Note:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics⁽⁸⁾

$V_{CC} = +2.5V \pm 5\%$, $R_L = 100_\Omega$ across the outputs; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Operating Frequency	$V_{OUT} \geq 200mV$	1.0	1.5		GHz
t_{pd}	Differential Propagation Delay					
	IN-to-Q	$100mV \leq V_{IN} \leq 200mV$, Note 9	600	810	1200	ps
	IN-to-Q	$200mV \leq V_{IN} \leq 800mV$, Note 9	500	720	1100	ps
	SEL-to-Q	$V_{TH} = V_{CC}/2$	350	580	850	ps
t_S OE	Set-up Time	OE-to-IN	Note 10			ps
t_H OE	Hold Time	IN-to-OE	Note 10			ps
t_{SKEW}	Output-to-Output Skew	Note 11		15	40	ps
	Input-to-Input Skew	Note 12		5	25	ps
	Part-to-Part Skew	Note 13			300	ps
t_{JITTER}	Clock					
	Random Jitter	Note 14			1	ps _{RMS}
	Cycle-to-Cycle Jitter	Note 15			1	ps _{RMS}
	Total Jitter	Note 16			10	ps _{PP}
	Crosstalk-Induced Jitter	Note 17			0.7	ps _{RMS}
t_r, t_f	Output Rise/Fall Time (20% to 80%)	At full output swing.	90		270	ps
	Duty Cycle	$V_{IN} > 200mV$	47		53	%
		$100mV \leq V_{IN} \leq 200mV$	45		55	%

Notes:

- High-frequency AC-parameters are guaranteed by design and characterization.
- Propagation delay is measured with input $t_r, t_f \leq 300ps$ (20% to 80%). The propagation delay is a function of the rise and fall times at IN. See "Typical Operating Characteristics" for details.
- Set-up and hold times apply to synchronous applications that intend to enable/disable before the next clock cycle. For asynchronous applications, set-up and hold do not apply.
- Output-to-Output skew is measured between two different outputs under identical transitions.
- Input-to-Input skew is the time difference between the two inputs to one output, under identical input transitions.
- Part-to-Part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- Random Jitter is measured with a K28.7 character pattern, measured at $<f_{MAX}$.
- Cycle-to-Cycle Jitter definition: the variation of periods between adjacent cycles, $T_n - T_{n-1}$ where T is the time between rising edges of the output signal.
- Total Jitter definition: with an ideal clock input of frequency $<f_{MAX}$, no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.
- Crosstalk is measured at the output while applying two similar differential clock frequencies that are asynchronous with respect to each other at the inputs.

Functional Description

Clock Select (SEL)

SEL is an asynchronous TTL/CMOS compatible input that selects one of the two input signals. An internal 25k Ω pull-up resistor defaults the input to logic HIGH if left open. Input switching threshold is $V_{CC}/2$. Refer to Figure 1a.

Fail-Safe Input (FSI)

The input includes a special fail-safe circuit to sense the amplitude of the input signal and to latch the outputs when there is no input signal present or when the amplitude of the input signal drops sufficiently below 100mV_{PK}, typically 30mV_{PK}. Refer to Figure 1b.

Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing such that the voltage across the input pair is significantly less than 100mV, FSI

function will eliminate a metastable condition and latch the outputs to the last valid state. No ringing and no undetermined state will occur at the output under these conditions. The output recovers to normal operation once the input signal returns to a valid state with a typical swing greater than 30mV.

Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on the rise and fall time of the input signal and on its amplitude.

Output Enable (OE)

OE is a synchronous TTL/CMOS-compatible input that enables/disables the outputs based upon the input to this pin. The enable function is synchronous so that the clock outputs will be enabled or disabled following a rising and a falling edge of the input clock. Refer to Figure 1c. Internal 25k Ω pull-up resistor defaults the input to logic HIGH if left open. Input switching threshold is $V_{CC}/2$.

Timing Diagrams

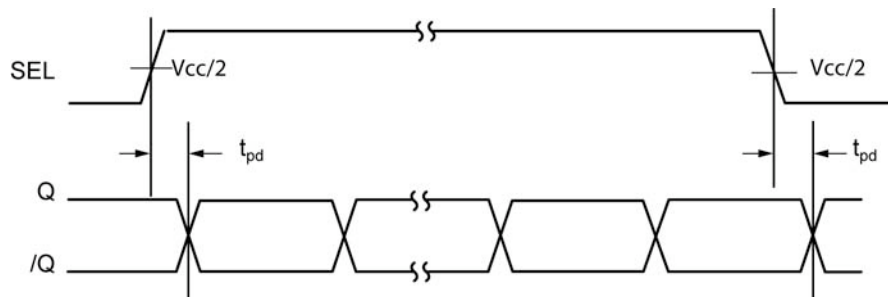


Figure 1a. SEL-to-Q Delay

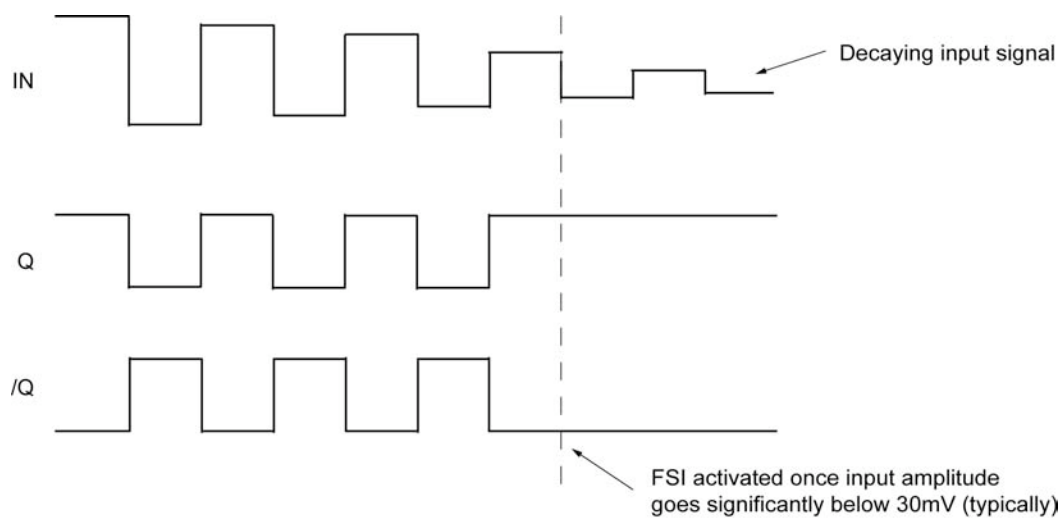


Figure 1b. Fail-Safe Feature

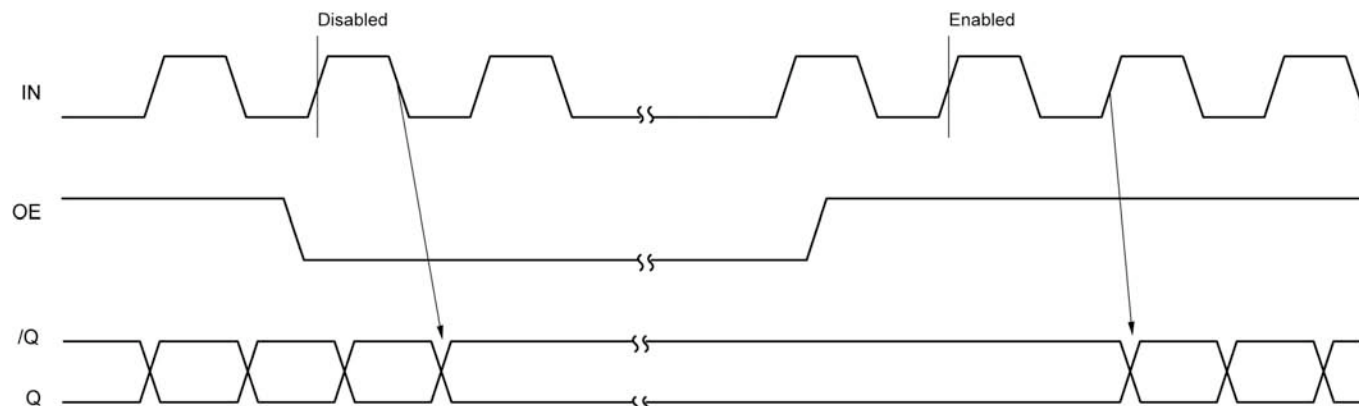


Figure 1c. Enable Output Timing Diagram

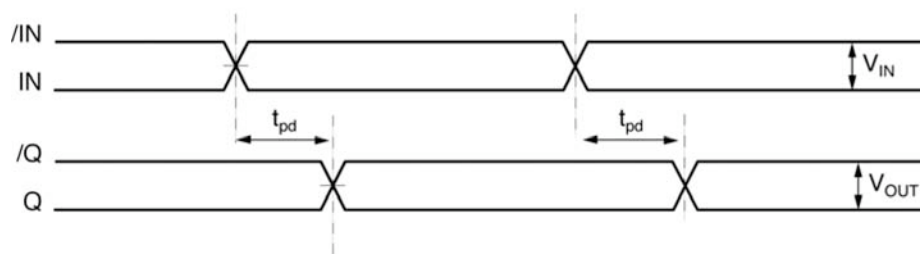


Figure 1d. Propagation Delay

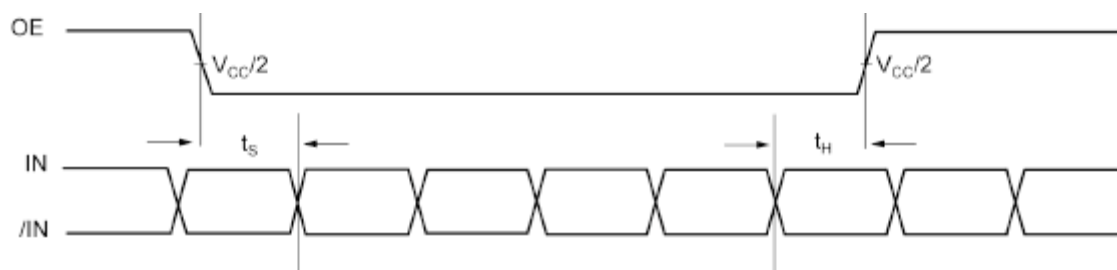
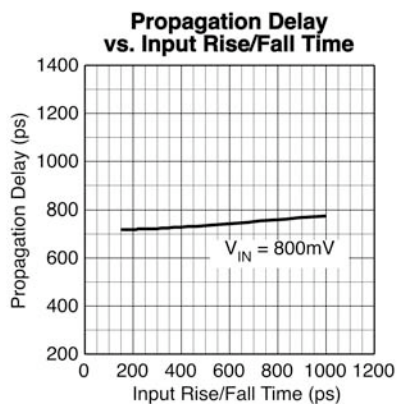
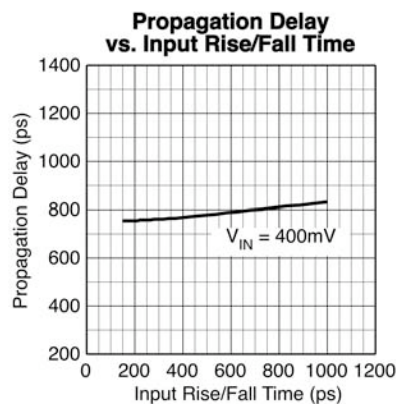
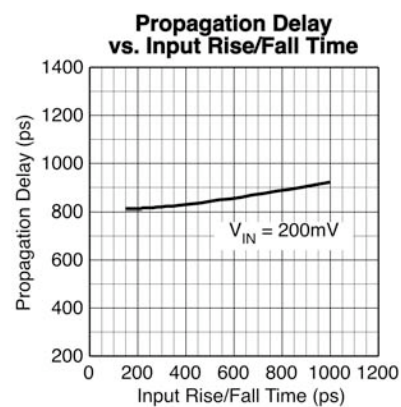
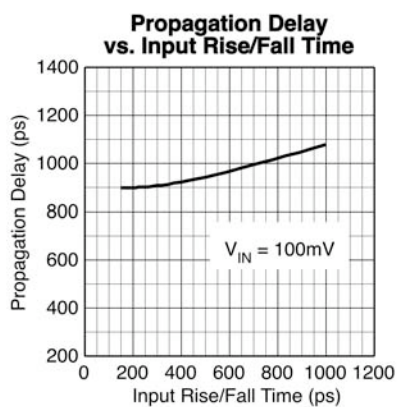
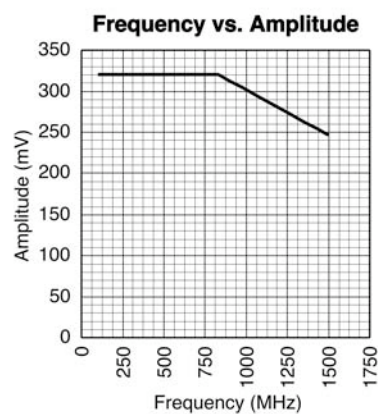


Figure 1e. Setup and Hold Time

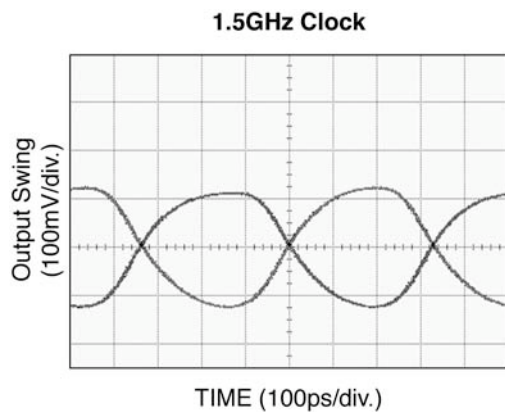
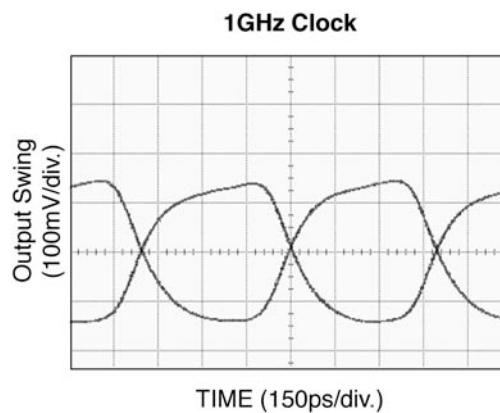
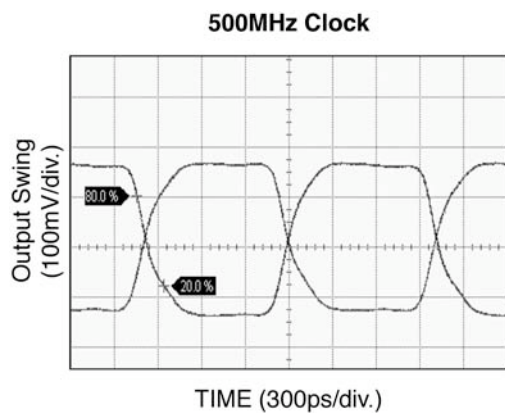
Typical Operating Characteristics

$V_{CC} = 2.5V$, $GND = 0V$, $V_{IN} = 200mV$, $R_L = 100\Omega$ across the outputs; $T_A = 25^\circ C$, unless otherwise stated.



Functional Characteristics

$V_{CC} = 2.5V$, $GND = 0V$, $V_{IN} = 200mV$, $R_L = 100\Omega$ across the outputs; $T_A = 25^\circ C$, unless otherwise stated.



Single-Ended and Differential Swings



Figure 2a. Single-Ended Voltage Swing

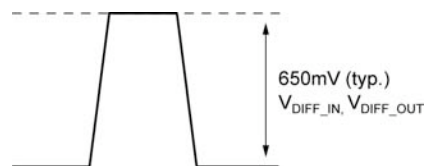


Figure 2b. Differential Voltage Swing

Input Stage

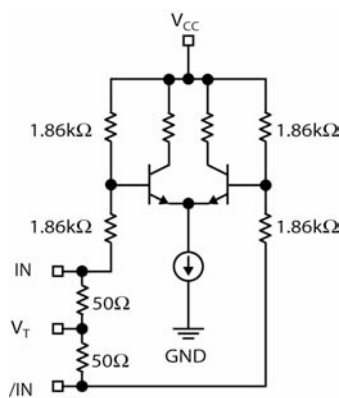


Figure 3. Simplified Differential Input Stage

Input Interface Applications

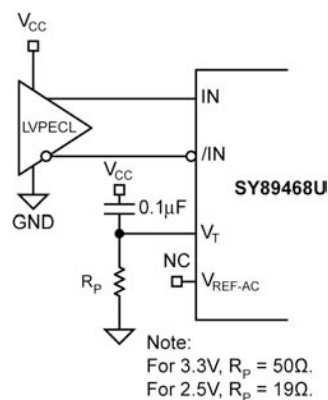


Figure 4a. LVPECL Interface (DC-Coupled)

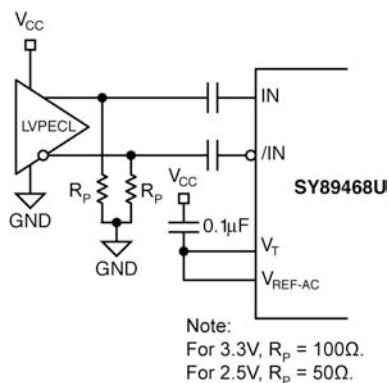
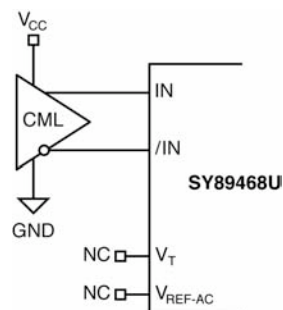


Figure 4b. LVPECL Interface (AC-Coupled)



Option: may connect V_T to V_{CC}

Figure 4c. CML Interface (DC-Coupled)

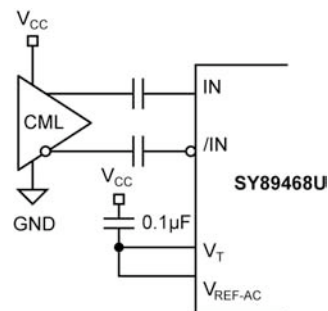


Figure 4d. CML Interface (AC-Coupled)

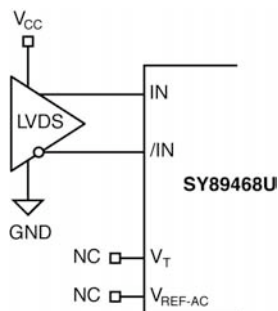


Figure 4e. LVDS Interface (DC-Coupled)

LVDS Output Interface Applications

LVDS specifies a small swing of 325mV typical, on a nominal 1.2V common mode above ground. The common mode voltage has tight limits to permit large variations in the ground between an LVDS driver and receiver. Also, change in common mode voltage, as a function of data input, is kept to a minimum, to keep EMI low.

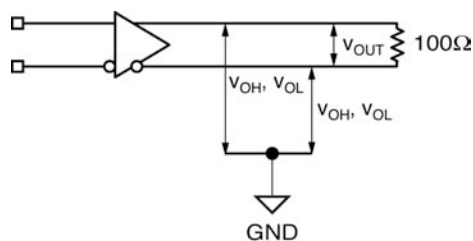


Figure 5a. LVDS Differential Measurement

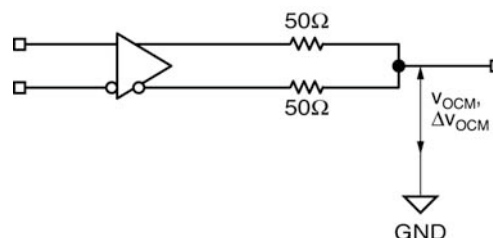
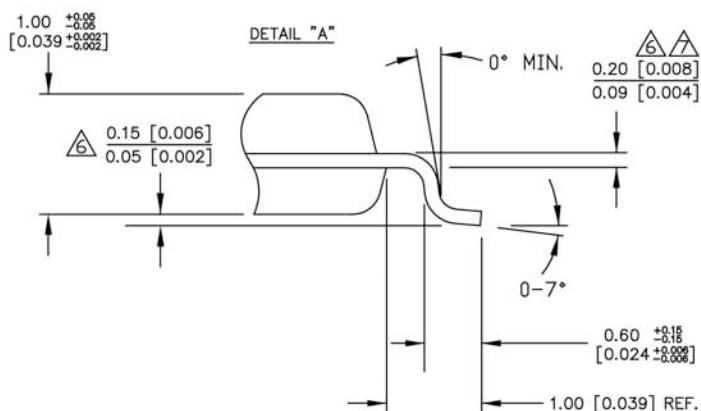


Figure 5b. LVDS Common Mode Measurement

Related Product and Support Documentation

Part Number	Function	Data Sheet Link
SY89467U	Precision LVPECL 1:20 Fanout MUX with 2:1 MUX and internal termination with Fail Safe Input	http://www.micrel.com/_PDF/HBW/sy89467u.pdf
	MLF [®] Application Note	www.amkor.com/products/notes_papers/MLFAppNote.pdf
HBW Solutions	New Products and Applications	www.micrel.com/product-info/products/solutions.shtml



1. DIMENSIONS ARE IN MM[INCHES].
2. CONTROLLING DIMENSION: MM.
3. EXPOSED PAD: Cu WITH Sn/Pb PLATING.
4. DIMENSION DOES NOT INCLUDE MOLD FLASH OF 0.254[0.010] MAX.
5. DIE UP ORIENTATION SHOWN. EXPOSED PAD IS VISIBLE FROM BOTTOM OF PACKAGE.
6. MAXIMUM AND MINIMUM SPECIFICATIONS ARE INDICATED AS FOLLOWS: $\frac{\text{MAX}}{\text{MIN}}$
7. THIS DIMENSION INCLUDES LEAD FINISH.

1. Package meets Level 2 Moisture Sensitivity Classification.
2. All parts are dry-packed before shipment.
3. Exposed pad must be soldered to a ground for proper thermal management.

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- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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